

50103-433/STL 3076

RESIST REMOVAL FROM PATTERNED  
RECORDING MEDIA

ABSTRACT OF THE DISCLOSURE

A method for patterning a carbon-containing substrate utilizing a patterned layer of a resist material as a mask and then safely removing the mask from the substrate without adversely affecting the substrate, comprising sequential steps of:

- (a) providing a substrate including a surface comprising carbon;
- 5 (b) forming a thin metal layer on the substrate surface;
- (c) forming a layer of a resist material on the thin metal layer;
- (d) patterning the layer of resist material;
- (e) patterning the substrate utilizing the patterned layer of resist material as a pattern-defining mask; and
- 10 (f) removing the mask utilizing the thin metal layer as a wet strippable layer or a plasma etch/ash stop layer.